

## **DPDT USB Switch With Over Voltage Protection**

#### **Features**

USB 2.0 Hi-speed DPDT switch

Typical -3dB bandwidth: 1.0GHz

Over voltage protection: 5.1V typical

• 24V DC protection on D+ and D- Ports

• +35V surge protection on D+ and D-

Supply voltage range: 2.7V to 5.5V

5.9Ω switch on-resistance typical

C<sub>ON</sub>: 5pF typical

Icc: 33µA typical

FOWLP 1.2mm X1.6mm X0.574mm-12B package

#### **Applications**

- Smart phones
- Tablets
- USB Type-C
- PC/Notebook

#### **General Description**

The AW35753 is a Hi-Speed USB 2.0(480Mbps) DPDT(Double Pole Double Throw) switch with integrated protection for USB D+ and D-, it can be configured as a dual 1:2 or 2:1 switch.

The AW35753 protection on the D+/D- pins can tolerate up to 24V DC, when D+ or D- voltage is greater than the OVP(Over-Voltage Protection) threshold, the switch will be automatically shutoff to protect downstream devices.

The device operates over a 2.7V to 5.5V supply range with independent control bits for each switch pair and an on/off enable pin for shutdown mode.

The AW35753 is available in a FOWLP 1.2mm X1.6mm X0.574mm-12B package.

# **Typical Application Circuit**

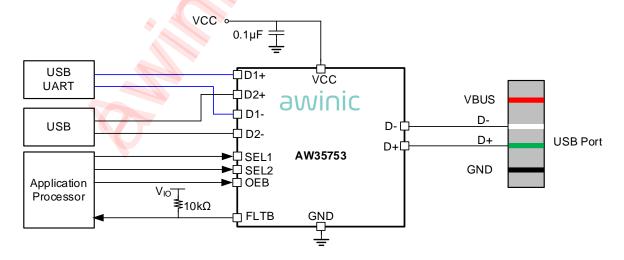
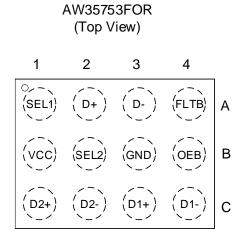


Figure 1 Typical Application Circuit of AW35753

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# **Pin Configuration And Top Mark**



AW35753FOR Marking (Top View)



Figure 2 Pin Configuration and Top Mark

## **Pin Definition**

PIN	NAME	DESCRIPTION			
A1	SEL1	Switch select1, active high			
A2	D+	Common high speed data port, differential +			
A3	D-	Common high speed data port, differential -			
A4	FLTB	Fault indicator output, active low, open drain			
B1	VCC	Supply voltage			
B2	SEL2	Switch select2, active high			
B3	GND	Ground			
B4	OEB	Output enable, active low			
C1	D2+	Multiplexed high speed data port2, differential +			
C2	D2-	Multiplexed high speed data port2, differential -			
C3	D1+	Multiplexed high speed data port1, differential +			
C4	D1-	Multiplexed high speed data port1, differential -			



### **Pin Functions**

OEB	SEL1	SEL2	D- CONNECTION	D+ CONNECTION
Н	X	X	High-Z	High-Z
L	L	L	D- to D1-	D+ to D1+
L	L	Н	D- to D1-	D+ to D2+
L	Н	L	D- to D2-	D+ to D1+
L	Н	Н	D- to D2-	D+ to D2+

# **Functional Block Diagram**

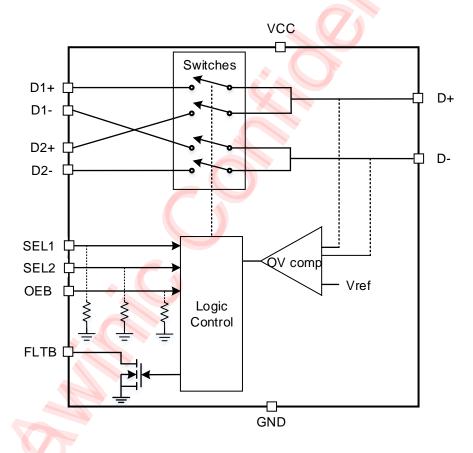


Figure 3 Functional Block Diagram



## **Typical Application Circuits**

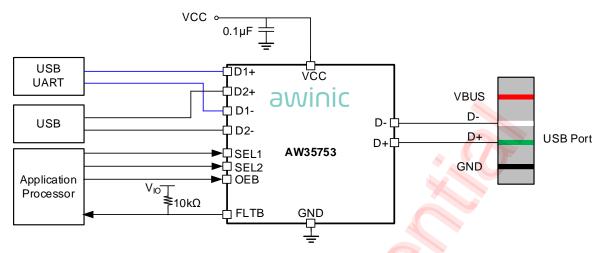


Figure 4 Typical Application Circuit of AW35753

Notice for Typical Application Circuits:

- 1. The AW35753 has internal 8.9-M $\Omega$  pull down resistors on SEL1, SEL2 and OEB, so no external resistors are required on the logic pins.
- 2. Internal pull-down resistor on SEL1, SEL2 pins ensures the D1+ and D1- channels are selected by default.

## **Ordering Information**

Part Number	Temperature	Package	Marking	Moisture Sensitivity Level	Environmental Information	Delivery Form
AW35753FOR	-40°C~85°C	FOWLP 1.2mm X1.6mm X0.574mm -12B	70HQ	MSL1	ROHS+HF	4500 units/ Tape and Reel



# **Absolute Maximum Ratings**(NOTE1)

PARAMETERS					
ge VCC	-0.3V to 6V				
ge(D+, D-)	-0.3V to 24V				
+, D1-, D2+, D2-)	-0.3V to 6V				
SEL1, SEL2, OEB	-0.3V to 6V				
FLTB	-0.3V to 6V				
al resistance θ <sub>JA</sub>	122°C/W				
temperature T <sub>JMAX</sub>	150°C				
erature range	-40°C to 85°C				
Storage temperature T <sub>STG</sub>					
ng 10 seconds)	260°C				
ESD					
Human Body Model (All pins, per JEDEC JS-001)(NOTE2)					
Charged Device Model (All pins, per JEDEC JS-002)(NOTE3)					
Latch-Up					
ESD78F-2022	±200mA				
	ge VCC ge(D+, D-) +, D1-, D2+, D2-) SEL1, SEL2, OEB FLTB al resistance θ <sub>JA</sub> temperature T <sub>JMAX</sub> erature range re T <sub>STG</sub> ng 10 seconds) ESD JEDEC JS-001)(NOTE2) er JEDEC JS-002)(NOTE3) Latch-Up				

NOTE1: Conditions out of those ranges listed in "absolute maximum ratings" may cause permanent damages to the device. In spite of the limits above, functional operation conditions of the device should within the ranges listed in "recommended operating conditions". Exposure to absolute-maximum-rated conditions for prolonged periods may affect device reliability.

NOTE2: The human body model is a 100pF capacitor discharged through a 1.5k $\Omega$  resistor into each pin. Test method: ESDA/JEDEC JS-001-2017.

NOTE3: Test method: ESDA/JEDEC JS-002-2018.

## **Recommended Operating Conditions**

	PARAMETERS	MIN	MAX	UNIT
Vcc	Supply voltage	2.7	5.5	V
V <sub>I/O</sub>	Analog input/output voltage(D±)	0	20	V
	Analog input/output voltage(Dn <sub>±</sub> )	0	3.6	V
Vı	Digital input voltage(SEL1, SEL2, OEB)	0	5.5	V
T <sub>A</sub>	Operating junction temperature T <sub>A</sub>	-40	85	°C



### **Electrical Characteristics**

 $V_{CC}=3.3V$  T<sub>A</sub> = 25°C for typical values (unless otherwise noted).

	PARAMETER	TEST CONDITION	MIN	TYP	MAX	UNIT
Vcc	Supply voltage		2.7	3.3	5.5	V
Icc	Active supply current	OEB=0V, SEL1,SEL2=0V, 0V <v<sub>D±&lt;3.6V</v<sub>		33	50	μA
lcc_pd	Standby supply current	OEB=Vcc SEL1, SEL2=0V	×	0.1		μΑ
DC Charac	teristics					
Ron	On-state resistance	V <sub>I/O</sub> =0.4V, I <sub>SINK</sub> =8mA		5.9		Ω
ΔR <sub>ON</sub>	On-state resistance match between channels	V <sub>I/O</sub> =0.4V, I <sub>SINK</sub> =8mA	9	0.1		Ω
R <sub>ON(FLAT)</sub>	ON-state resistance flatness	V <sub>I/O</sub> =0V to 0.4V, I <sub>SINK</sub> =8mA		0.1		Ω
	I/O pin OFF leakage	$V_{D\pm}=0V$ or 3.6V $V_{D1\pm}$ or $V_{D2\pm}=3.6V$ or $0V$		0.4	10	μΑ
l <sub>OFF</sub>	current on D+/D-	$V_{D\pm}=0V$ or 24V $V_{D1\pm}$ or $V_{D2\pm}=0V$		310	500	μΑ
Ion	ON leakage current on D+/D-	$V_{D\pm}$ = 0V or 3.6V $V_{D1\pm}$ and $V_{D2\pm}$ =high-Z		0.4	10	μΑ
Digital Cha	nracteristics					
ViH	Input logic high	SEL1, SEL2, OEB	0.96			V
VıL	Input logic low	SEL1, SEL2, OEB			0.4	V
Vol	Output logic low	FLTB I <sub>OL</sub> = 1 mA			0.5	V
R <sub>PD</sub>	Internal pull-down resistor on digital input pins			8.9		ΜΩ
Protection						
V <sub>OVP_TH</sub>	OVP threshold	D+/D- rising	4.8	5.1	5.4	V
V <sub>OVP</sub> _HYST	OVP threshold hysteresis			270		mV
V <sub>CLAMP_V</sub>	Clamping voltage on D <sub>1±</sub> and D <sub>2±</sub> pins during surge	8/20µs surge test, OEB=0V, R <sub>L</sub> =open			9	V
tclamp	Clamp time during OVP	8/20µs surge test, OEB=0V, R∟=open		150		ns



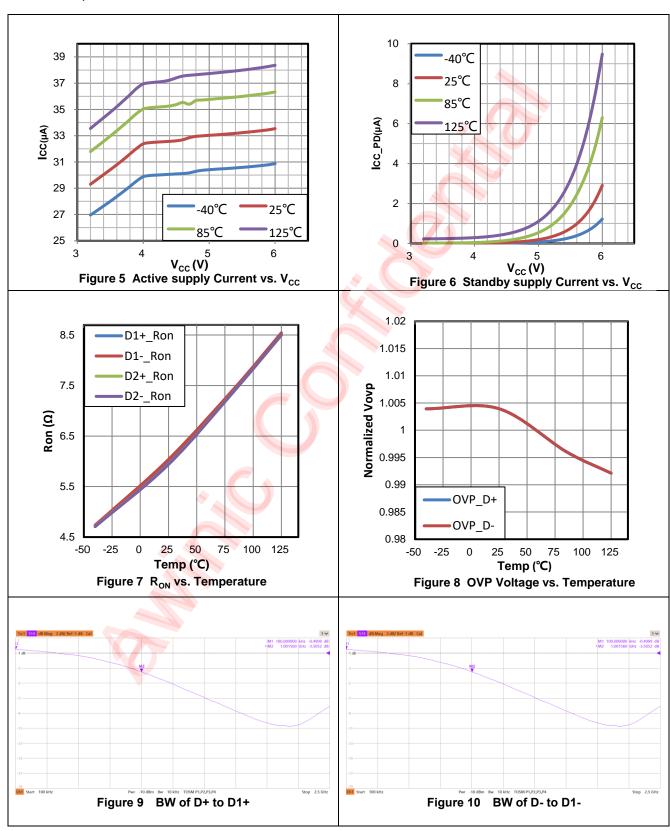
# **Electrical Characteristics (Continued)**

 $V_{CC}=3.3V$  T<sub>A</sub> = 25°C for typical values (unless otherwise noted).

	PARAMETER	TEST CONDITION	MIN	TYP	MAX	UNIT
Dynamic (	Characteristics					
Con	IO pins ON capacitance	V <sub>D±</sub> =0V or 3.3V, f=240MHz, switch ON		6		pF
Oiso	Differential off isolation	$R_L$ =50 $\Omega$ , $C_L$ =5pF f=100kHz, switch OFF	*	-60		dB
0.00	Direction of toolanest	$R_L$ =50 $\Omega$ , $C_L$ =5pF f=240MHz, switch OFF	X	-20		dB
XTALK	Channel to channel crosstalk	R <sub>L</sub> =50Ω, C <sub>L</sub> =5pF f=100 kHz, switch ON		-60		dB
BW	-3dB bandwidth	R <sub>L</sub> =50Ω, switch ON		1.0		GHz
tswitch	Switching time between channels (SEL1, SEL2 to output)	V <sub>D±</sub> =0.8V, R <sub>L</sub> =50Ω.		1.5	5	μs
ton	Device turn on time (OEB to output)	C <sub>L</sub> =5pF,		50		μs
t <sub>off</sub>	Device turn off time (OEB to output)	Vcc=2.7V to 5.5V		60		ns
t <sub>pd</sub>	Propagation delay	$V_{D\pm}$ =0.4V, $R_L$ =50 $\Omega$ , $C_L$ =5pF, $V_{CC}$ =2.7V to 5.5V		200		ps

## **Typical Characteristics**

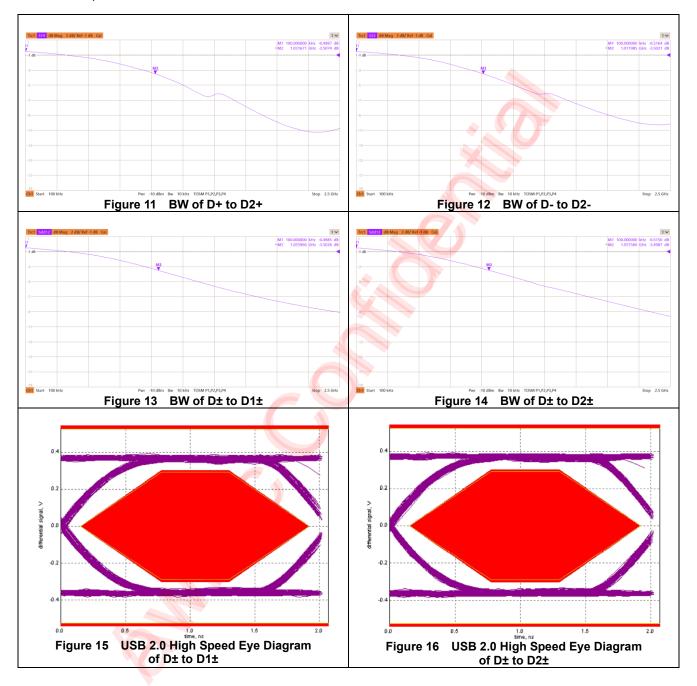
Ambient temperature is 25°C, V<sub>CC</sub> =3.3V, V<sub>D±</sub>=0.4V, unless otherwise noted.





# **Typical Characteristics (Continued)**

Ambient temperature is 25°C, V<sub>CC</sub> =3.3V, V<sub>D±</sub>=0.4V, unless otherwise noted.



# **Timing Diagram**

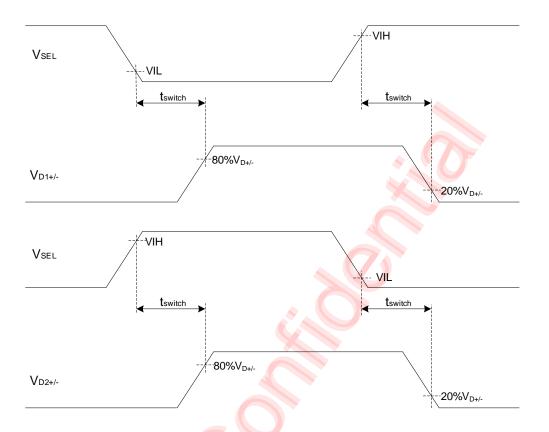


Figure 17 Switching Time Between Channels

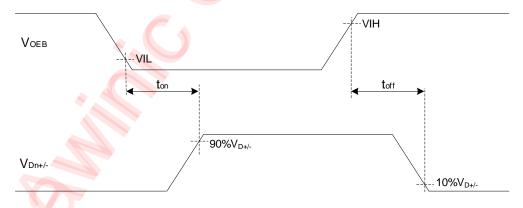


Figure 18 Device Turn On Time

# **Timing Diagram (Continued)**

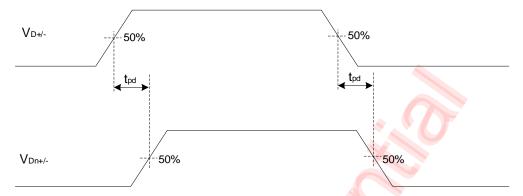


Figure 19 Propagation delay

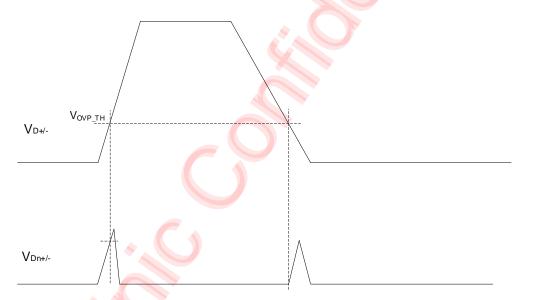
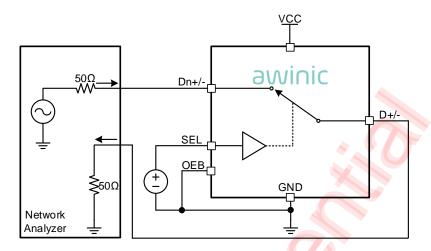


Figure 20 Overvoltage Protection

# **Application Information**



**BW and Insertion Loss** Figure 21

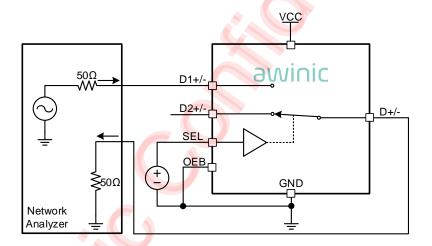


Figure 22 OFF Isolation

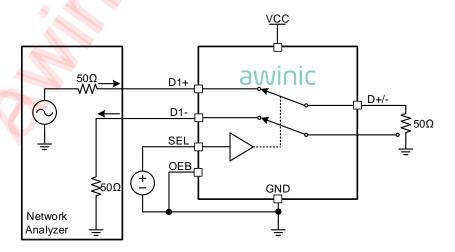


Figure 23 Cross Talk



#### **Detailed Functional Description**

The AW35753 is bidirectional low-power dual port, high-speed, USB2.0 analog switch with integrated protection for USB D+ and D-, it can be configured as a dual 1:2 or 2:1 switch. The AW35753 will protect D+ and D- pins when stressed with voltages up to 24V. The device can pass signals with bandwidth 1.0GHz to maintain signal integrity and eye compliance.

#### **Powered-off Protection**

When the AW35753 is powered off the I/Os of the device remain in a high-Z state. The crosstalk, off-isolation, and leakage remain within the Electrical Specifications.

#### **Over-Voltage Protection**

AW35753 is designed to protect the system from damage. Over-voltage event happens when voltage on D+/D-exceeds 5.1V(typ.), and device will activate OVP to disconnect the switches.

#### **High Impedance Mode**

When OEB is logic high, the AW35753 is in high impedance mode, all the signal paths are in Hi-Z state.

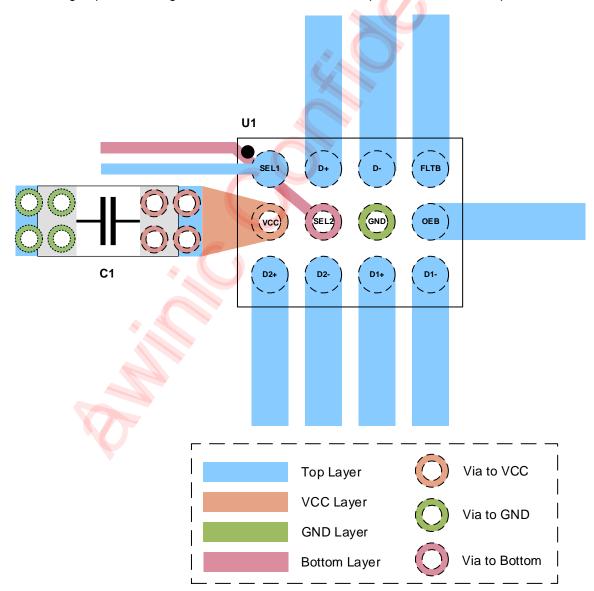
OEB	SEL1	SEL2	D- Connection	D+ Connection
Н	X	X	High-Z	High-Z
L	L	L	D- to D1-	D+ to D1+
L	L	Н	D- to D1-	D+ to D2+
L	Н	<u></u>	D- to D2-	D+ to D1+
L	Н	Н	D- to D2-	D+ to D2+



### **PCB Layout Consideration**

To obtain the optimal performance of AW35753, PCB layout should be considered carefully. Here are some guidelines:

- 1. Place supply bypass capacitors as close to VCC pin as possible and avoid placing the bypass capacitors near the D+/D- traces.
- 2. The differential characteristic impedance of D+ and D- traces is suggested to be  $90\Omega$ , and it's better to shield D+ and D- traces by ground planes.
- 3. Route the high-speed USB signals using a minimum of vias and corners which reduces signal reflections and impedance changes.
- 4. Do not route USB traces under or near crystals, oscillators, clock signal generators, switching regulators, mounting holes, magnetic devices or ICs that use or duplicate clock signals.
- 5. Avoid stubs on the high-speed USB signals because they cause signal reflections.
- 6. Route all high-speed USB signal traces over continuous GND planes, with no interruptions.

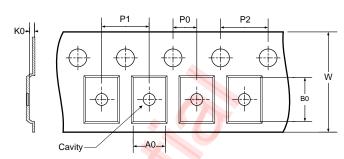




## **Tape And Reel Information**

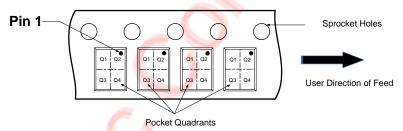
# REEL DIMENSIONS 0

#### TAPE DIMENSIONS



- A0: Dimension designed to accommodate the component width
- B0: Dimension designed to accommodate the component length
- K0: Dimension designed to accommodate the component thickness
- W: Overall width of the carrier tape
- P0: Pitch between successive cavity centers and sprocket hole
- P1: Pitch between successive cavity centers
- P2: Pitch between sprocket hole
- D1: Reel Diameter
- D0: Reel Width

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Note: The above picture is for reference only. Please refer to the value in the table below for the actual size

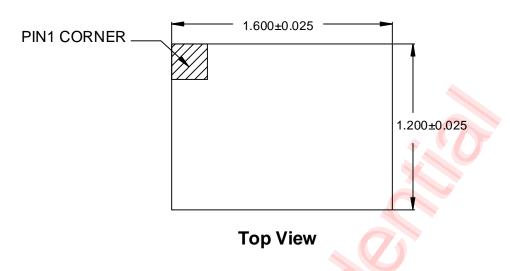
#### DIMENSIONS AND PIN1 ORIENTATION

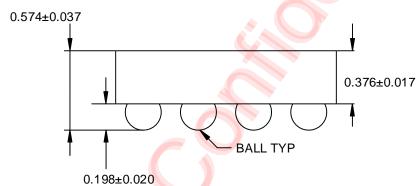
D1	D0	A0	B0	K0	P0	P1	P2	W	Pin1 Quadrant
(mm)	(mm)	(mm)	(mm)	(mm)	(mm)	(mm)	(mm)	(mm)	Fini Quadrant
179.00	9.00	1.30	1.75	0.70	2.00	4.00	4.00	8.00	Q2

All dimensions are nominal

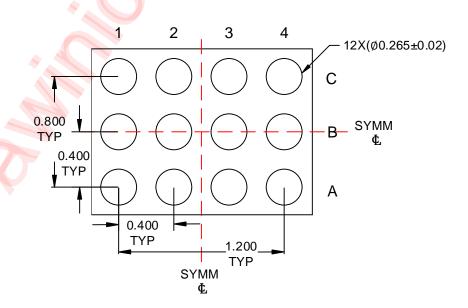


## **Package Description**





Side View

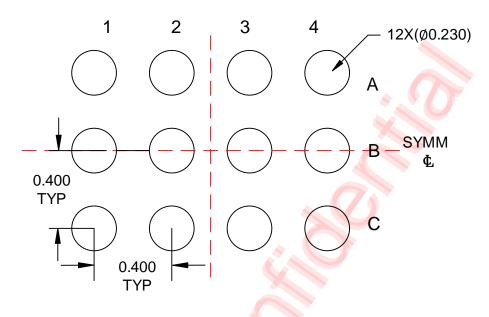


**Bottom View** 

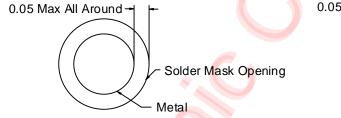
Unit:mm

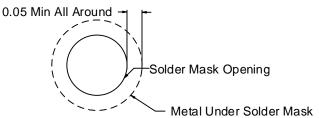


#### **Land Pattern Data**



SYMM £





NON SOLDER MASK DEFINED

SOLDER MASK DEFINED

Unit:mm



# **Revision History**

Version	Date	Change Record				
V1.0	Oct. 2021	Datasheet V1.0 released				
V1.1	Feb. 2023	<ol> <li>Update the Pin Configuration And Top Mark (P2)</li> <li>Update the Package Description (P16)</li> <li>Update the Land Pattern Data (P17)</li> </ol>				



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